



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-03-28
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	22AA*U39DBA1	A	MA1A	2014-03-28
Amount	UoM	Unit type	ST ECOPACK Grade	
69.0	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LGA	4.4 - 7.5 - 1	16	No lead	
Comment	Package: LGA 4.4x7.5x1 16L - FOR SENSORS; MDF valid for LIS3LV02DLTR, LIS3LV02DL, AIS3LV02DLTR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devic

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Diboron trioxide	1000 ppm	0.095		1377

Material Composition Declaration						Mfr Item Name	22AA*U39DBA1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	28.892	mg	supplier	die	Silicon (Si)	7440-21-3		26.486	mg	916724	383855
die (s)				supplier	metallisation	Aluminium (Al)	7429-90-5		0.091	mg	3150	1319
die (s)				supplier	metallisation	Copper (Cu)	7440-50-8		0.123	mg	4257	1783
die (s)				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.001	mg	35	14
die (s)				supplier	metallisation	Titanium (Ti)	7440-32-6		0.002	mg	69	29
die (s)				supplier	metallisation	Tungsten (W)	7440-33-7		0.001	mg	35	14
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.054	mg	1869	783
die (s)				supplier	passivation	Silicon Oxide	7631-86-9		0.774	mg	26789	11217
die (s)				R	passivation	Lead Oxide	1317-36-8	7c-I-Electrical and	0.871	mg	30147	12623
die (s)				supplier	passivation	Boron Trioxide	1303-86-2		0.095	mg	3288	1377
die (s)				supplier	passivation	Silicon Oxide	7631-86-9		0.136	mg	4707	1971
die (s)				supplier	passivation	Aluminium oxide	1344-28-1		0.136	mg	4707	1971
die (s)				supplier	passivation	Butyl Carbitol Acetate	124-17-4		0.068	mg	2354	986
die (s)				supplier	passivation	Ethyl cellulose	9004-57-3		0.027	mg	935	391
die (s)				supplier	passivation	Terpineol	8000-41-7		0.027	mg	935	391
substrate	Other Organic Materials	18.441	mg	supplier	core material	Bismaleimide (B)	105391-33-1		1.947	mg	105580	28217
substrate				supplier	core material	Triazine (T)	25722-66-1		1.947	mg	105580	28217
substrate				supplier	core material	Fiber glass	65997-17-3		5.808	mg	314950	84174
substrate				supplier	core material	metal hydroxide	21645-51-2		0.132	mg	7158	1913
substrate				supplier	core material	Zinc hydroxide	20427-58-1		0.04	mg	2169	580
substrate				supplier	core material	Thermosetting resin	54208-63-8		3.26	mg	176780	47246
substrate				supplier	core material	Calcium sulfate	7778-18-9		0.066	mg	3579	957
substrate				supplier	Solder mask	Baryum sulfate	7727-43-7		0.354	mg	19196	5130
substrate				supplier	Solder mask	(2-methoxymethylethoxy)propanol	34590-94-8		0.059	mg	3199	855
substrate				supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6		0.197	mg	10683	2855
substrate				supplier	Solder mask	Quartz	14808-60-7		0.197	mg	10683	2855
substrate				supplier	Solder mask	Acrylates derivative	9003-01-4		0.815	mg	44195	11812
substrate				supplier	Solder mask	Epoxy resin	29690-82-2		0.268	mg	14533	3884
substrate				supplier	Solder mask	aromatic hydrocarbon	Proprietary		0.079	mg	4284	1145
substrate				supplier	metallisation	Copper (Cu)	7440-50-8		3.076	mg	166802	44580
substrate				supplier	metallisation	Nickel (Ni)	7440-02-0		0.166	mg	9002	2406
substrate				supplier	metallisation	Gold (Au)	7440-57-5		0.03	mg	1627	435
Die attach	Other inorganic materials	2.032	mg	supplier	glue or tape	Acrylic resin	9003-01-4		0.642	mg	315945	9304
Die attach				supplier	glue or tape	epoxy resin	Proprietary		1.288	mg	633858	18667
Die attach				supplier	glue or tape	Diphenol Propane Diglycidyl Ether	1675-54-3		0.102	mg	50197	1478
Bonding wire	Precious metals	0.267	mg	supplier	wire	Gold (Au)	7440-57-5		0.264	mg	988764	3826
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	11236	43
encapsulation	Other inorganic materials	19.368	mg	supplier	mold compound	Silica, vitreous	60676-86-0		16.946	mg	874948	245594
encapsulation				supplier	mold compound	Epoxy Resin	85954-11-6		0.775	mg	40014	11232
encapsulation				supplier	mold compound	Epoxy resin	Proprietary		0.775	mg	40014	11232
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		0.775	mg	40014	11232
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.097	mg	5008	1406